

L Number	Hits	Search Text	DB	Time stamp
1	261698	(alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:23
2	47893	((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:24
3	1012	((((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and 216/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:24
4	31	(((((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and 216/\$.ccls.) and 216/17.cccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:40
5	37567	(metal\$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:46
6	3946	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask\$4)) and (((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
7	301	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask\$4)) and (((((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and 216/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
8	7	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near4 (mask\$4)) and ((((((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and 216/\$.ccls.) and 216/17.cccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:43
9	11851	(metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:56
10	1196	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and (((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47
11	588	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47
12	154	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 219/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:47

13	33	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 216/\$.ccls.) and (((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 219/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:54
14	8	((((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 216/\$.ccls.) and (((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) and 219/\$.ccls.)) and alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:54
15	197	((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) with (alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:56
16	25	((((metal\$4 or copper or cu or conducting or conductive or trace or metallization) near1 (mask\$4)) with (alignment)) with etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/30 12:57